

Assembly Manual for the  $\mu$ SDX „Sandwich“ Design by DL2MAN (Software by PE1NNZ)

The  $\mu$ SDX is a simple but very efficient QRP Multimode Shortwave Transceiver, that is able to transmit and receive SSB, CW, AM and FM. It can be configured for any Shortwave Band by Exchanging RF PCB. Now even as Multiband Rig with switchable Low-Pass Filters.

Software to make the Microcontroller work can be found here: <https://github.com/threeme3/QCX-SSB>

Discussion about this Project here: <https://groups.io/g/ucx/topic/sdxbreakoutboard/75316472?p=,,,20,0,0,0::recentpostdate%2Fsticky,,,20,2,0,75316472>

The DL2MAN Design is divided into 3 PCB's in Size of a Credit Card (85x55mm) so it's easier to change things in future.

We have

1. Main PCB (with AtMega, PLL, Multiplexer, OpAmp and NAND Gates, Basically the complete RX/TX Core)
2. IO-PCB (With all Knobs, Rotary Encoder, Audio and Mic/Key Jacks)
3. RF PCB with 3 switchable LPF's
4. (Optional: RF PCB Monoband without Relay switching)

IO PCB is Top of the Sandwich, Mainboard is middle and RF PCB is bottom in the final assembly.

PCB's are being connected via standard Jumper Headers and Sockets in 2,54mm/0,1" Spacing.

The Main PCB requires special „stackable“ Headers, that have „male“ and „female“ connector, so we can connect the other PCB's from both sides.

The PCB's are mechanically stabilized by Spacers in M3 Threading. If you use metal spacers, they will provide additional GND Connection between PCB's and are very handy to connect for example Oscilloscope GND for measurement.

For Construction, I start with Main PCB, as it is the most complicated one.

Some building advice and Project Demonstration can be found in this Video: <https://www.youtube.com/watch?v=qQI9Y6VXzl8&t=3s>

At least for Main PCB, I would suggest to order stencil and use it with Reflow Oven. It can be Hand soldered, but at least with Small Si5351 IC, you will have a very hard time ;)

Apply solder paste with stencil, and place all Capacitors (without electrolytic Caps), resistors and Inductances. Place SMT IC's.

Solder them in reflow Oven.

Hand Solder electrolytic Caps, Crystals and THT IC's (including 7805), I suggest use of IC Socket at Least for the AT Mega  $\mu$ -Controller.

Hand Solder BF170 and Power Jack.

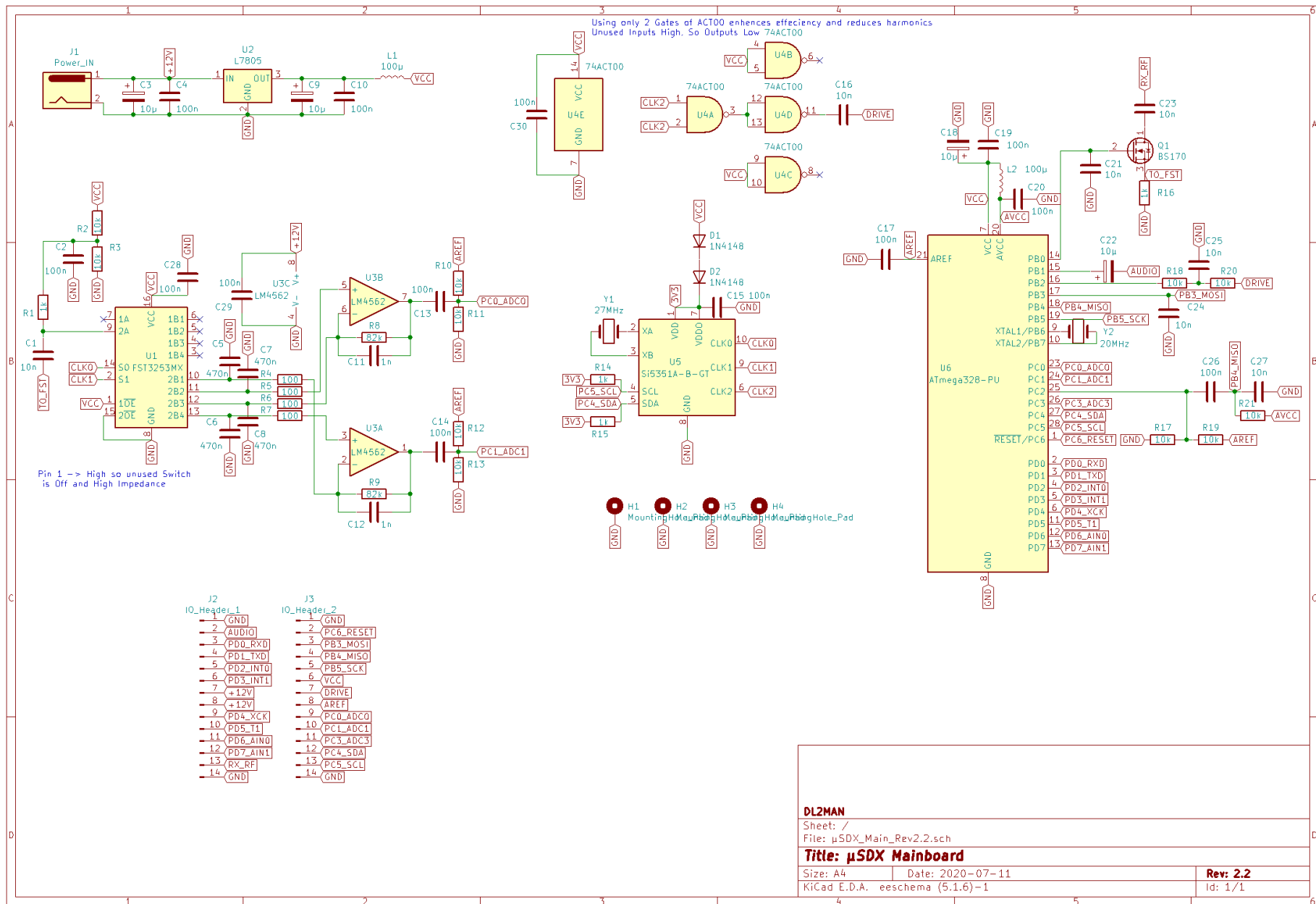
From the Stackable Connector Kit, use the 6Pin and 8Pin Connectors, to create 2x 14 Pin (IO Header 1 and 2).

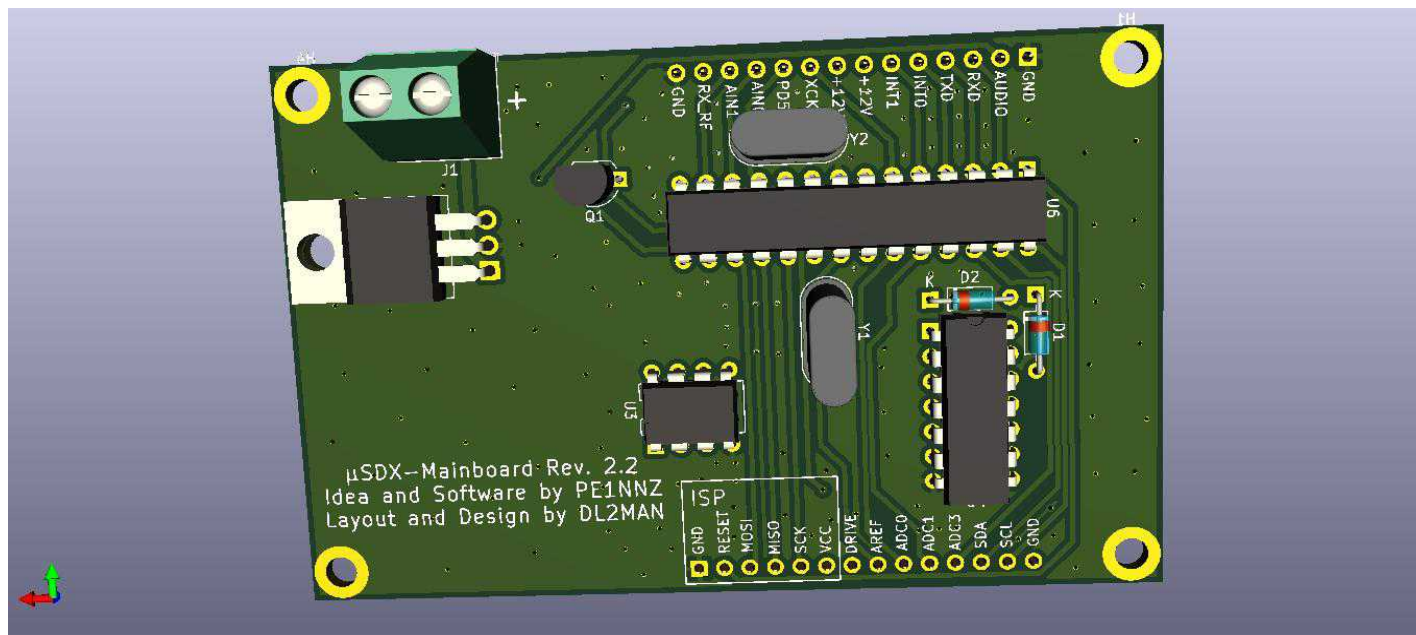
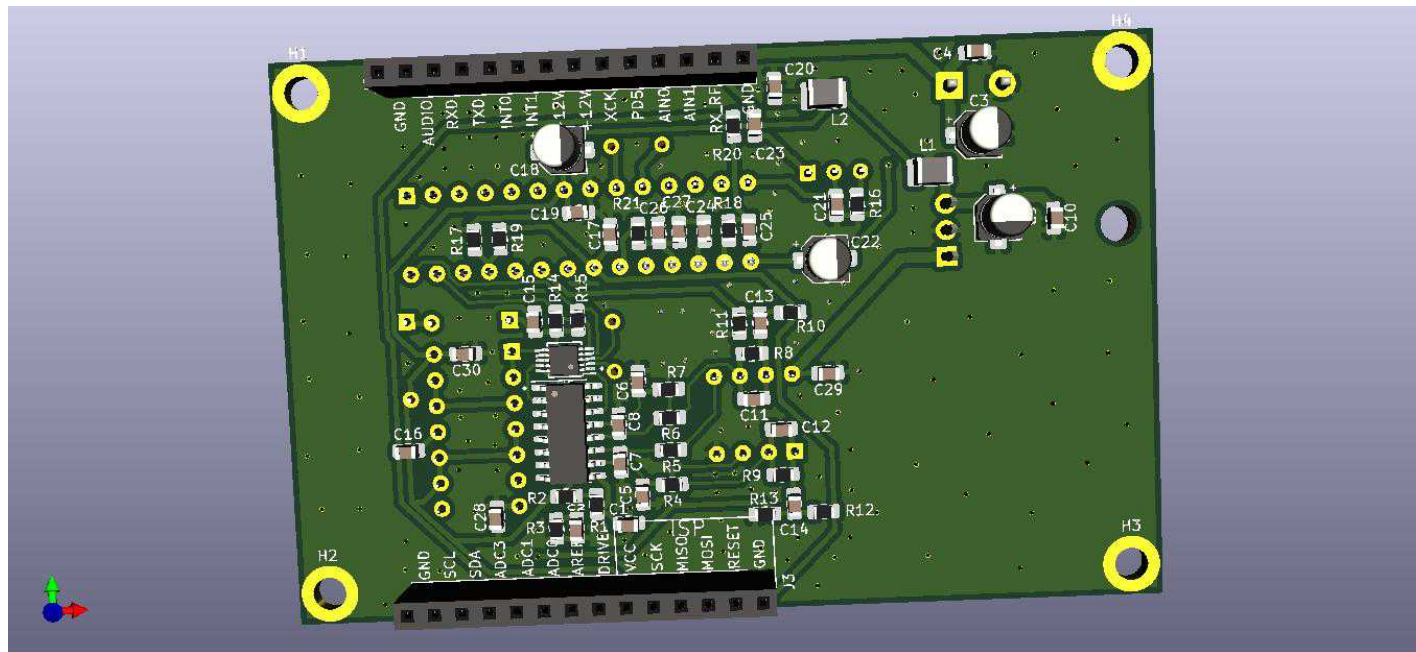
Male Connectors should be on the side, where the THT IC's are and where the Power Jack is.

Use a file, or Sand Paper, to remove a little bit of the Plastic, where the 6 and 8 Pin Connectors have contact to each other, so they will fit in the 14 Pin Header Holes without force.

Try to solder them in as straight as possible, and try to solder only close to PCB. After placing the ATmega into Socket, you can Power it up and Program it with an Arduino UNO as ISP.

Mainboard			
Part	Amount	Value	Description
C1,C16,C21,C25,C27,C24,C23	7	10n	Capacitor, SMT, 0805
C2,C4,C10,C13,C14,C15,C17,C19,C20,C26,C28,C29,C30	13	100n	Capacitor, SMT, 0805
C5,C6,C7,C8	4	470n	Capacitor, SMT, 0805
C11,C12	2	1n	Capacitor, SMT, 0805
D1,D2	2	1N4148	Diode 1N4148 THT
L1,L2	2	100μ	Fixed Inductance 100μH, Size 1610
R13,R2,R3,R10,R11,R12,R18,R17,R20,R19,R21	11	10k	Resistor, SMT, 0805
R1,R14,R15,R16	4	1k	Resistor, SMT, 0805
R4,R5,R6,R7	4	100	Resistor, SMT, 0805
R8,R9	2	82k	Resistor, SMT, 0805 0,1%
U1	1	FST3253MX	SOIC-16 Package
U4	1	74ACT00	DIP-14 Package
U5	1	Si5351A-B-GT	MSOP-10 Package
U6	1	Atmega328P-PU	DIP-28 Package, Use Socket !!!
Y1	1	27MHz	Crystal, THT, Package HC49U-S
Y2	1	20MHz	Crystal, THT, Package HC49U-S
U3	1	LM4562	DIP-8 Package
U2	1	L7805	TO-220 Package
J2	1	IO_Header_1	PinSocket_1x14, use Adafruit Stackable Pinheader MPN #85
J3	1	IO_Header_2	PinSocket_1x14, use Adafruit Stackable Pinheader MPN #85
J1	1	Power_IN	TerminalBlock_Phoenix_MKDS-1,5-2-5.08_1x02_P5.08mm_Horizontal
C3,C9,C18,C22	4	10μ	Electrolytic Capacitor 10μH 35V
Q1	1	BS170	TO-92 Housing
H1,H2,H3,H4	4	MountingHole_Pad	Spacer 10mm, M3 Threading, conductive





Continue with IO Board:

This built is actually pretty straight forward. Start with hand soldering the smaller parts (Resistors), Leave out R6 to save another 10mA of RX Current. This resistor is for LCD Background illumination, but it's not needed if you have green LCD. It can be read without.

Continue with Poti, Mic, Buttons.

Then you need to solder in J1 and J2 (You need to do this before soldering Display, otherwise solder joints cannot be reached anymore).

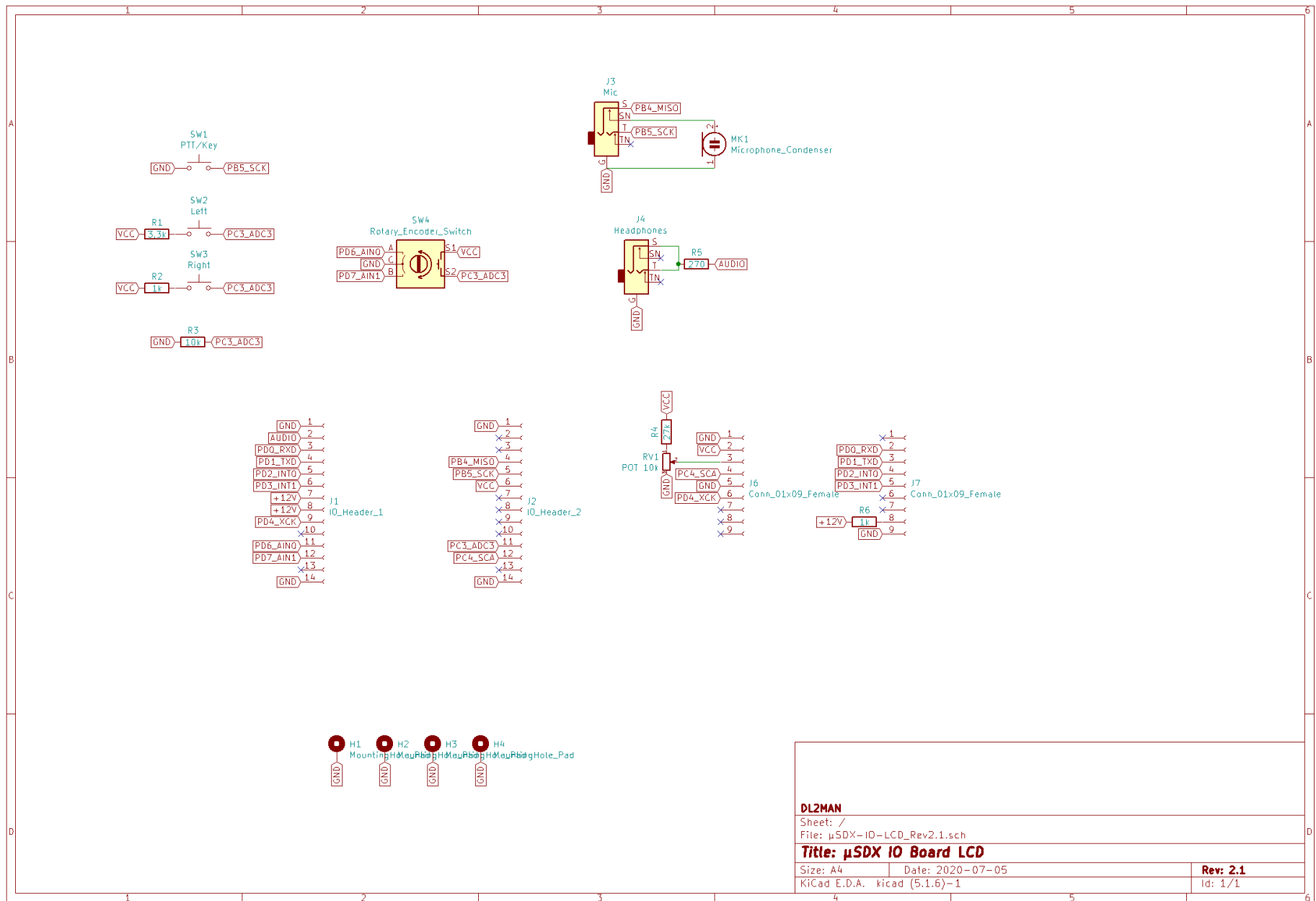
Then solder in Display and rotary encoder.

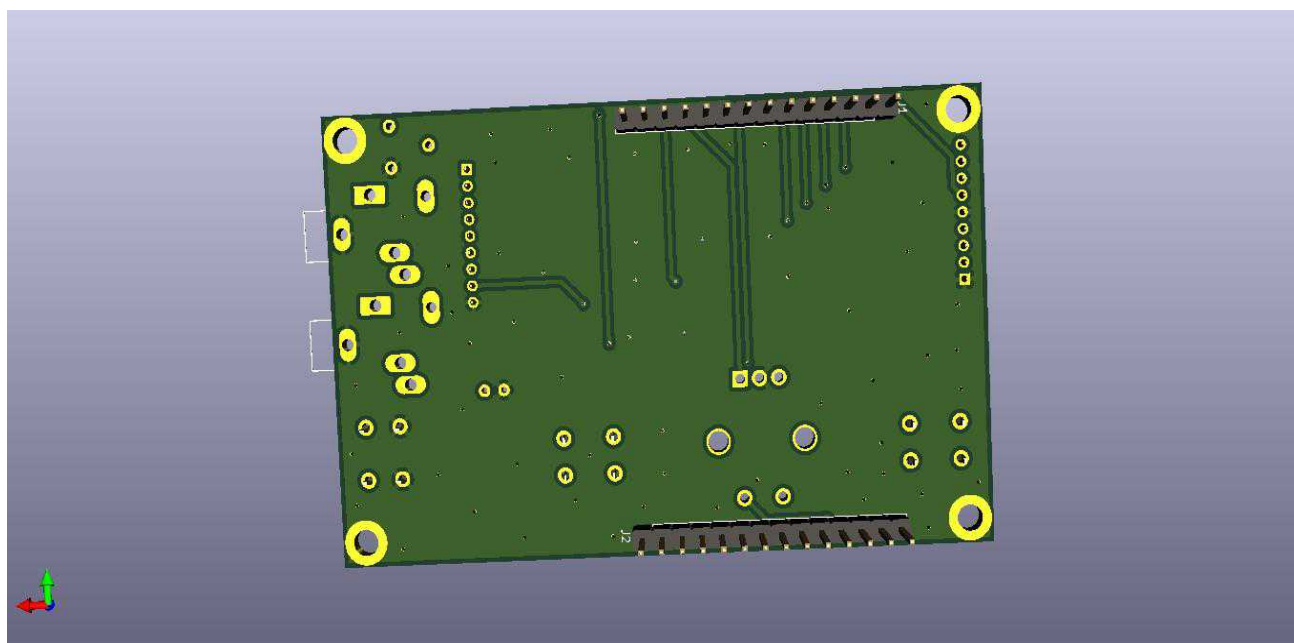
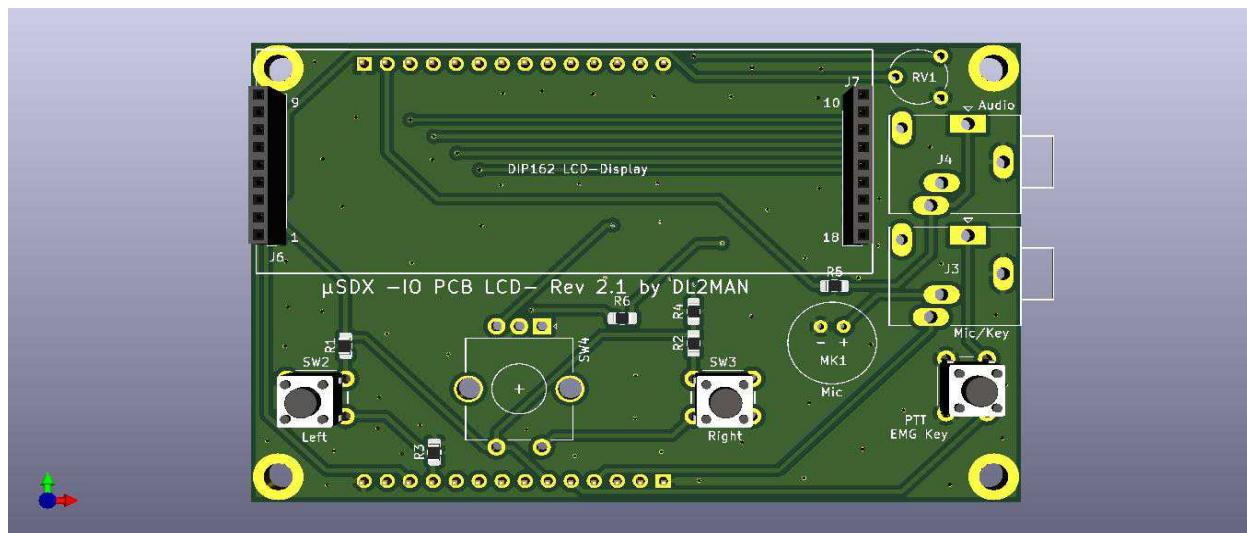
You should bend the metal clamps of the frame on the backside of the LCD a little, to avoid contact with the IO Header. If you put it in to try fit, you will see, which ones to bend.

The on Board Mic (MK1) is a standard electret type capsule. It is being disconnected, when a plug is inserted in Key/Mic Jack.

Note: One of the 4 Spacers is below display and cannot be fit with M3 Screw. So this one is only a spacer. The other 3 also aid in mechanical stabilisation and GND Connection.

IO PCB		
SW4	1 Rotary_Encoder_SW	RotaryEncoder_Alps_EC11E-Switch
H3,H4,H2,H1	4 MountingHole_Pad	Spacer 10mm, M3 Threading Male/Female
MK1	1 EMY-9765P	Condenser Microphone
J1	1 IO_Header_1	Use „breakable“ male Pin headers.
J2	1 IO_Header_2	Use „breakable“ male Pin headers.
R1	1 3,3k	Resistor, SMT, 0805
R2,R6	2 1k	Resistor, SMT, 0805 (Leave Out R6 for no Background illumination)
R3	1 10k	Resistor, SMT, 0805
R5	1 270	Resistor, SMT, 0805
SW2	1 Left	Print Push Button_6mm_H5mm
SW3	1 Right	Print Push Button_6mm_H5mm
J3	1 Mic	Jack_3.5mm_with 2x internal Switch (eg LUM 1503-09)
J4	1 Headphones	Jack_3.5mm_with 2x internal Switch (eg LUM 1503-09)
SW1	1 PTT/Key	Print Push Button_6mm_H5mm
J6,J7	1 LCD 162 DIP	LCD Display „162 DIP“ Green
R4	1 27k	Resistor, SMT, 0805
RV1	1 POT 10k	Potentiometer_Piher_PT-6-V_Vertical





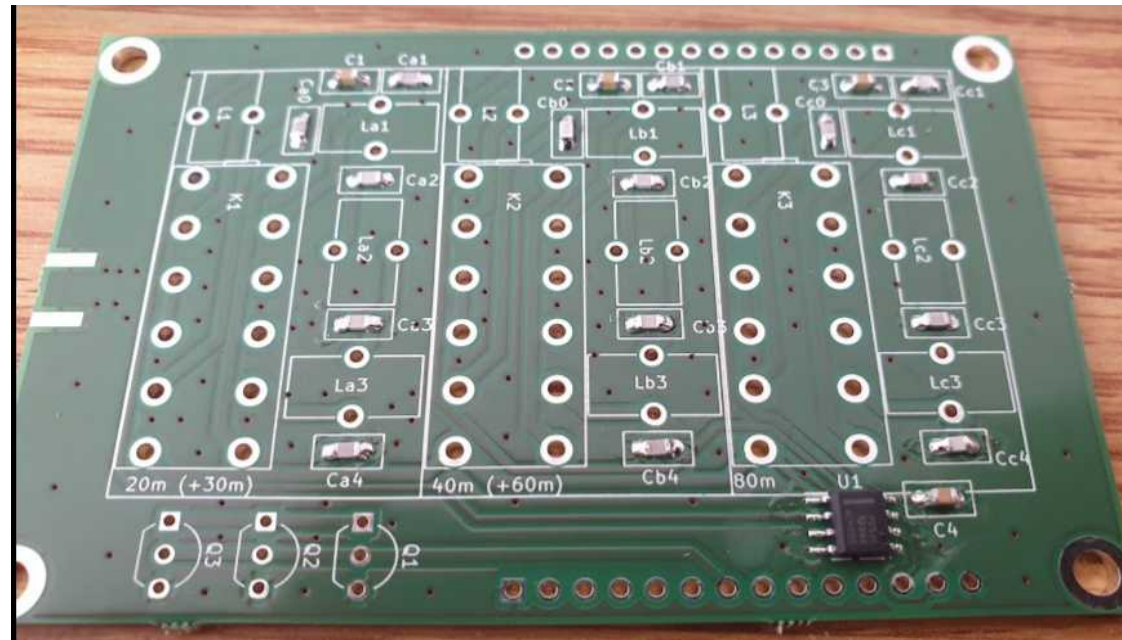


And finally we take care about RF PCB – **NEW Multi-Band PCB !**

First place the Capacitors and the only SMT IC on the Board (U1) according to the Schematic and BOM Table below.

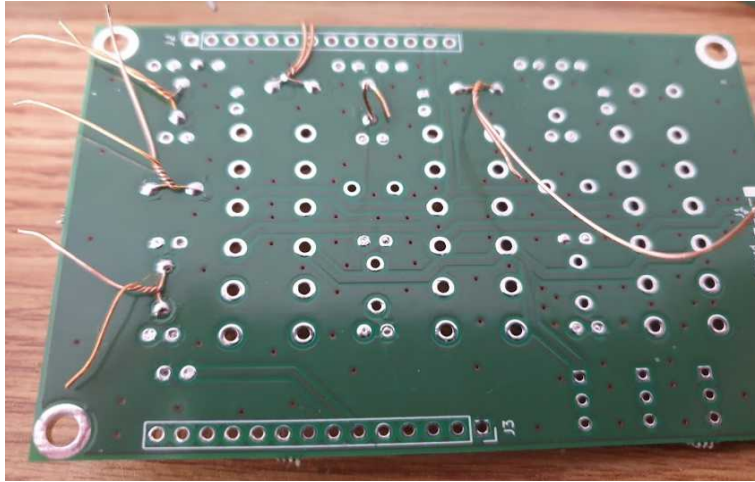
The footprint allows to use THT Capacitors with 2,5mm Spacing and also 0805 SMT Type. I use what I have, but usually prefer SMT.

Use NP0 Capacitors with 100V.

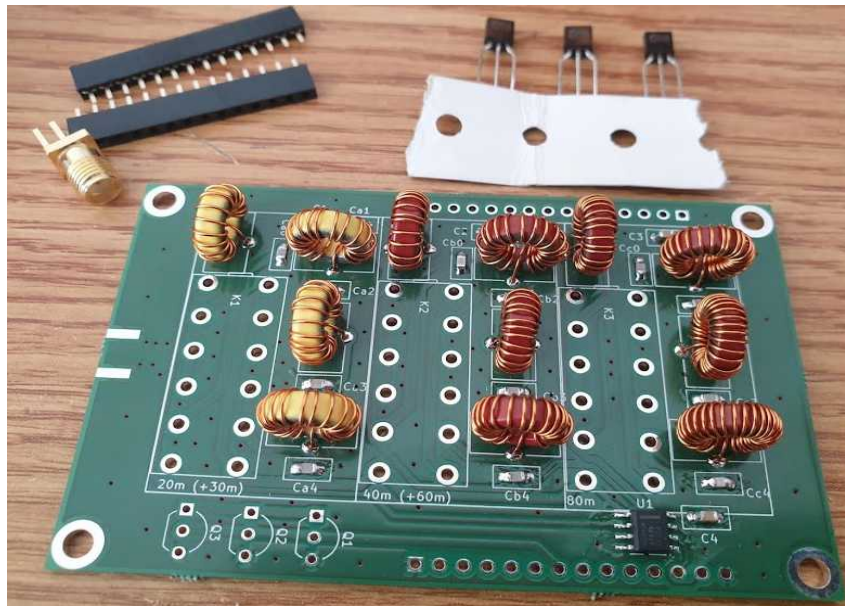


Then select Toroids according to Schematic and wind them with the amount of turns according to Schematic. For Example: 0,11uH/n16/T37-6 means: Use Toroid Core T37-6 (= yellow one), put on 16 Turns, and if you can, measure Inductance and tweak until you have 0,77μH. The footprint on the PCB almost forces you to divide the windings evenly and I found this gives me much more repeatable results. Remember: When you insert the Copper enamel wire in the core, this is already winding Nr. 1 ! Wind one Toroid Coil after another, scratch off the enamel coating of their ends with a knife, stick the lose ends through PCB and twist them like shown below. Then they won't fall out, and you can solder them after having placed all of them (or a few of them like in my Photo)

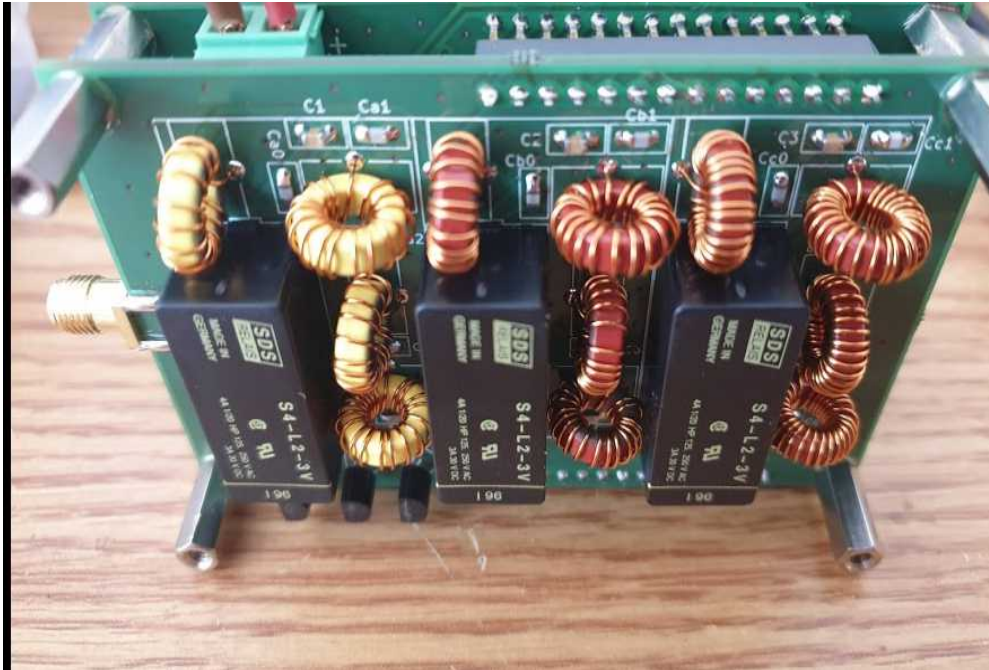




After all Toroids are Placed and soldered, it should look like next Photo. You can also guess what's next.... Place and solder Jumper Connectors, SMA Jack and PA FET's.



Last items that go on the RF Board are the Relays. Then Board is Ready for assembly and Test:



If you want to use the Relays, at this time (July 2020) you need the Software from Experimental Branch (Search for „Latching“ in the Code).

When testing RF Boards, I always measure Input Current and Output Power into Dummy Load.

You can calculate efficiency:

Power In = Voltage in x (Current In while TX – Current while RX)

Efficiency in % = Power Out / Power In x 100

With this built and the above Values in Schematic I get between 60-80% of Efficiency.

You can affect efficiency and output Power by Squeezing windings more together or separate them more evenly. Usually no more tweaking than that is required.

# Multiband RF Board BOM:

Reference	Quantity	Value	Footprint
C1 C2 C3 C4	4	100n	Capacitor, X7R, 100V. THT 2,5mm or SMT 0805
Ca0	1	30p	Capacitor, NP0, 100V. THT 2,5mm or SMT 0805
Ca1 Ca4 Cc0	3	180p	Capacitor, NP0, 100V. THT 2,5mm or SMT 0805
Ca2 Ca3	2	390p	Capacitor, NP0, 100V. THT 2,5mm or SMT 0805
Cb0	1	56p	Capacitor, NP0, 100V. THT 2,5mm or SMT 0805
Cb1 Cb4	2	270p	Capacitor, NP0, 100V. THT 2,5mm or SMT 0805
Cb2 Cb3	2	680p	Capacitor, NP0, 100V. THT 2,5mm or SMT 0805
Cc1 Cc4	2	470p	Capacitor, NP0, 100V. THT 2,5mm or SMT 0805
Cc2 Cc3	2	1200p	Capacitor, NP0, 100V. THT 2,5mm or SMT 0805
J1	1	Conn_Coaxial	SMA Connector, Edge Mount (stolen from Si5351 Breakout Boards)
J2 J3	2	Conn_01x14_Female	Connector_PinSocket_2.54mm:PinSocket_1x14_P2.54mm_Vertical
K1 K2 K3	3	Relay_S4-L2-3V	Relay, Latching 3V, 2 Coils, 4 Switches, (eg Panasonic S4-L2-3V or equal)
L1	1	0,59uH/n14/T37-6	14 Turns on T37-6 (Yellow) Core
L2	1	1,15uH/n17/T37-2	17 Turns on T37-2 (Red)Core
L3	1	2,3uH/n24/T37-2	24 Turns on T37-2 (Red)Core
La1 La3	2	0,77uH/n16/T37-6	16 Turns on T37-6 (Yellow) Core
La2	1	0,9uH/n17/T37-6	17 Turns on T37-6 (Yellow) Core
Lb1 Lb3	2	1,4uH/n19/T37-2	19 Turns on T37-2 (Red)Core
Lb2	1	1,7uH/n21/T37-2	21 Turns on T37-2 (Red)Core
Lc1 Lc3	2	2,4uH/n25/T37-2	25 Turns on T37-2 (Red)Core
Lc2	1	3uH/n27/T37-2	27 Turns on T37-2 (Red)Core
Q1 Q2 Q3	3	BS170	Package_TO_SOT_THT:TO-92_Inline_Wide
U1	1	PCA9536D	Package_SO:SOIC-8_3.9x4.9mm_P1.27mm



Alternatively you can build a Monoband PCB:

First place the Capacitors, matching the Band you want to build (see Table below).

The footprint allows to use THT Capacitors with 2,5mm Scacing and also 0805 SMT Type.

Use NP0 Capacitors with minimum 50V. 100V Types are better and less prone to failure !

Then select and wind Torids according to your needs. The footprint on the PCB almost forces you to devide the windings evenly and I found this gives me much more repeatable results. Remember: When you insert the Copper enamel wire in the core, this is already winding Nr. 1 !

However, I found experimentally, that L1 and C1 Combination less critical then expected. More critical for output Power and efficieny are the values of LPF (C3,C4,C5,C6 and L2/L3/L4)

Ghetto Class E				
Band	L1 (X=50 Ohm)	Toroid	n	C1
80m	2,3μH	T37-2 (red)	24	150pF
60m	1,45μH	T37-2 (red)	19	100pF
40m	1,15μH	T37-2 (red)	17	82pF
30m	0,77μH	T37-6 (yellow)	16	56pF
20m	0,59μH	T37-6 (yellow)	14	39pF

Tschebycheff LPF (50 Ohms in / 50 Ohms Out)

Band	C3/C6	C4/C5	L3	L3 Toroid	L3 (n)	L2/L4	L2/L4 Toroid	L2 / L4 (n)
80m	470pF	1200pF	3,0μH	T37-2 (red)	27	2,4μH	T37-2 (red)	25
60m	680pF	1200pF	2,3μH	T37-2 (red)	24	2,1μH	T37-2 (red)	23
40m	270pF	680pF	1,7μH	T37-2 (red)	24	1,4μH	T37-2 (red)	21
30m	270pF	560pF	1,3μH	T37-6 (yellow)	20	1,1μH	T37-6 (yellow)	19
20m	180pF	390pF	0,9μH	T37-6 (yellow)	17	0,77μH	T37-6 (yellow)	16

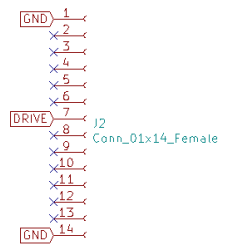
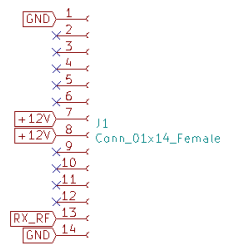
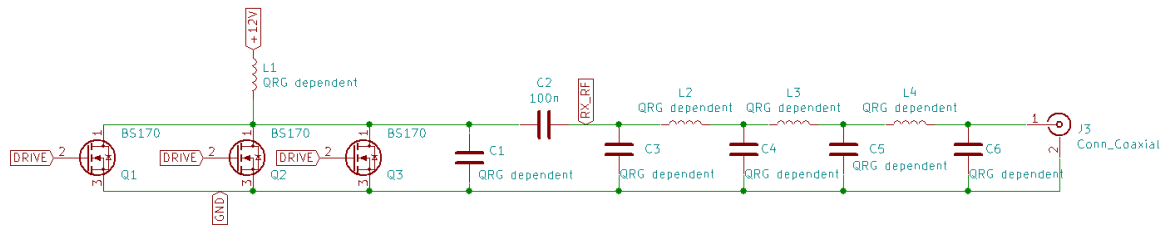
You finish with the 3x BS170's, the SMA Connector and the Female Jumper Connectors

RF PCB			
L1,L2,L3,L4	4	QRG dependent	See Table above
J1,J2	2	Conn_01x14_Female	PinSocket_1x14_P2.54mm_Vertical Female
J3	1	Conn_Coaxial	SMA Connector from Si5351 Breakout Board (Edge Mountable)
C3,C4,C5,C6,C1	5	QRG dependent	See Table above
C2	1	100n	Either SMT 0805 or 2,54mm THT
H1,H2,H3,H4	4	MountingHole_Pad	Mount 15mm Spacers, Male Female as feet
Q1,Q2,Q3	3	BS170	TO-92 Package

Have fun while building, and please report any bugs and errors while building to [groups.io](https://groups.io)

or directly to me:

[DL2MAN@gmx.de](mailto:DL2MAN@gmx.de)



DL2MAN

Sheet: /  
File: μSDX\_RF\_Rev2.sch

**Title: μSDX Monoband PA Board**

Size: A4 Date: 2020-07-05  
KiCad E.D.A. eeschema (5.1.6)-1

**Rev: 2.0**  
Id: 1/1



